

1. **In the Claims.** The following listing of claims will replace all prior versions of the claims in the application:

1. (previously presented) A solder for use in wave-soldering comprising:
from 88.5% to 93.2% tin;
from 3.5% to 4.5% silver;
from 2.0% to 6% indium;
from 0.3% to 1% copper; and
phosphorous present in an amount of not more than 0.01%.
2. (Canceled)
3. (Canceled)
4. (currently amended) A solder according to claim 1 which comprises 91.3% tin, 4.2% silver, 4.0% indium, 0.5% copper and 0.01% phosphorous, and said solder having a Young's Modulus of no more than about 9512 MPa.
5. (previously presented) A solder according to claim 1 which comprises 91.39% tin, 4.1% silver, 4.0% indium, 0.5% copper and 0.004% phosphorous.
6. (currently amended) A method of preparing a solder for use in wave-soldering process, comprising the steps of:
 - (a) mixing tin, silver, indium, copper and phosphorous to form the solder such that the proportion of tin in the solder is from 88.5% to 93.2%; the proportion of silver in the solder is from 3.5% to 4.5%; the proportion of indium in the solder is from 2.0% to 6%; the proportion of copper in the solder is from 0.3% to 1.0%, and the proportion of phosphorous in the solder is not more than 0.01%, wherein the solder has a Young's Modulus of no more than about 9512 MPa.

7. (Canceled)
8. (Canceled)
9. (previously presented) A method according to claim 6 which comprises mixing tin, silver, indium, copper and phosphorous such that:
 - the proportion of tin in the solder is 91.3%;
 - the proportion of silver in the solder is 4.2%;
 - the proportion of indium in the solder is 4%;
 - the proportion of copper in the solder is 0.5%; and
 - the proportion of phosphorous is 0.01%.
10. (previously presented) A method according to claim 6 which comprises mixing tin, silver, indium, copper and phosphorous such that:
 - the proportion of tin in the solder is 91.39%;
 - the proportion of silver in the solder is 4.1%;
 - the proportion of indium in the solder is 4%;
 - the proportion of copper in the solder is 0.5%; and
 - the proportion of phosphorous in the solder is 0.004%.
11. (currently amended) A method of soldering, comprising the steps of:
 - (a) forming a solder by combining tin, silver, indium, copper and phosphorous in the following proportions:
 - from 88.5% to 93.2% tin;
 - from 3.5% to 4.5% silver;
 - from 2.0% to 6.0% indium;
 - from 0.3% to 1.0% copper; and
 - phosphorous in an amount not more than 0.01%; wherein the solder has a Young's Modulus of no more than about 9512 MPa; and
 - (b) using the solder formed in step (a) to solder in a wave-soldering process.

12. (Canceled)

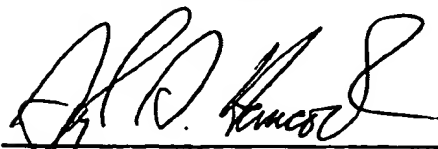
13. (Canceled)

14. (previously presented) A method according to claim 11 which comprises using a solder comprising 91.3% tin, 4.2% silver, 4.0% indium, 0.5% copper, and 0.01% phosphorous.

15. (previously presented) A method according to claim 11 which comprises using a solder comprising 91.39% tin, 4.1% silver, 4.0% indium, 0.5% copper and 0.004% phosphorous.

16. (Canceled)

Respectfully submitted,

A handwritten signature in black ink, appearing to read "D.D. Hancock", written over a horizontal line.

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